

FEATURES

- Supply Voltage Range from 1.3 V to 5.5V
- 18V_{PP} Output from a 1.3V Supply
- Integrated Boost Converter Generates up to 16.5V Supply
- Input Signal 20Hz to 10kHz
- No Voltage Cross Output at Shutdown Mode
- Low Current Consumption
- Automatic Standby and Wake-up Control
- Available QFN16 and QFN12 package
- Short protection current about 100mA
- OTP feature

APPLICATIONS

- Health Care Systems
- Home Appliances

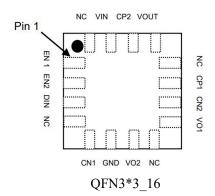
- Wrist Watches
- Handheld GPS devices
- PDAs
- Security Devices
- Alarm Clocks

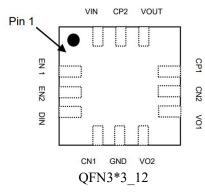
DESCRIPTION

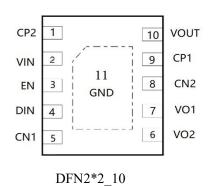
The SD116 is a switching driver with multi-mode charge pump for piezo-sounder. It can drive outputs up to 18Vpp from 1.3V supply. For adjusting the piezoelectric sounder sound volume, the charge pump can operate in either of a 1x, 2x or 3x mode. Because SD116 has the shutdown function, it is suitable for the battery application.

SD116 includes built-in automatic shutdown and wake up that guarantees longer battery life. SD116 features thermal shutdown and output short protection circuits.

PACKAGE (QFN16 AND QFN12)







ORDING INFORMATION

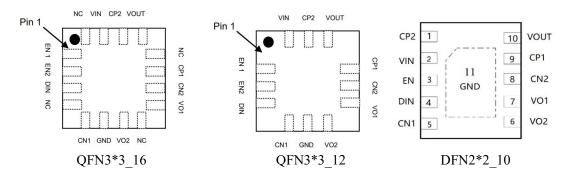
Part Number	Package Type	Package Qty	Op Temp(°C)	Mark
SD116	QFN16	7000	-40~85	SD116 XXX
SD116	QFN12	5000	-40~85	SD116 XXX
SD116	DFN10	3000	-40~85	SD116 XXX



MARKING DESCRIPTION(QFN3*3_12)

First line	SD116	Part Number
Second line	AXXX E.g A503	A represents the thickness of the chip 0.75mm, the first x of xxx represents the year, and the last two xx represent the number of weeks; E.g : A503 stands for thickness 0.75mm, produced in the third week of 2025.
	PXXX E.g P503	P represents the chip thickness of 0.50mm, the first x of xxx represents the year, and the last two xx represent the number of weeks; E.g : P503 stands for thickness 0.50mm, production in the third week of 2025.

PINOUT



PIN FUNCTIONS (QFN16)

	Pin Number		Pin Name	Туре	Function
QFN3*3_16	QFN3*3_12	DFN2*2_10		JF	
1	1	2	EN1	Ι	Charge pump mode select 1
2	2	3	EN2	I	Charge pump mode select 2
3	3	4	DIN	I	Signal Input
4			NC	_	No Connection
5	4	5	CN1	I	Capacitor 1 Negative Terminal
6	5		GND	P	Ground
7	6	6	VO2	0	Positive Output
8			NC	_	No Connection
9	7	7	VO1	0	Negative Output
10	8	8	CN2	I	Capacitor 2 Negative Terminal
11	9	9	CP1	I	Capacitor 1 Positive Terminal
12			NC	_	No Connection
13	10	10	VOUT	0	Boost Output
14	11	1	CP2	I	Capacitor 2 Positive Terminal
15	12	2	VIN	P	Power supply
16			NC		No Connection

(1)G = Ground, I = Input, O = Output, P = Power



ABSOLUTE MAXIMUM RATINGS (Note 1)

(@ $T_A = +25$ °C, unless otherwise specified.)

Symbol	Characteristics	Value	Unit
VIN	Supply Voltage	-0.3 to 6.0	V
VOUT	Output Voltage	-0.3 to 16.5	V
VEN1	EN1 Voltage	-0.3 to V _{IN} +0.3	V
TA	Operating Free-Air Temperature Range	-40 to +85	°C
$T_{\rm J}$	Operating Junction Temperature Range	-40 to +150	°C
TSTG	Storage Temperature Range	-65 to +150	°C

Note: 1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

(@ $T_A = +25$ °C, unless otherwise specified.)

Symbol	Characteristics	Conditions	Min	Max	Unit
VIN	Supply Voltage	1x Mode, 2x Mode,3x Mode	1.3	5.5	V

ESD Susceptibility

HBM	Human Body Model	4	kV
MM	Machine Model	600	V
CDM	Charged Device Model	1	kV

THERMAL INFORMATION

Parameter	Symbol	Package	Maximum	Unit
Thermal Resistance (Junction to Ambient)	θ_{JA}	QFN16	35	°C/W
Thermal Resistance (Junction to Case)	$\theta_{ m JC}$	QFN16	14	°C/W
Thermal Resistance (Junction to Ambient)	θ_{JA}	QFN12L	68	°C/W
Thermal Resistance (Junction to Case)	$\theta_{ m JC}$	QFN12L	25	°C/W
Thermal Resistance (Junction to Ambient)	θЈА	DFN2*2_10	68	°C/W
Thermal Resistance (Junction to Case)	θЈС	DFN2*2_10	25	°C/W



ELECTRICAL CHARACTERISTICS

(@ $T_A = +25$ °C, $V_{IN} = 3.0$ V, $C_{PIEZO} = 30$ nF, $f_{DIN} = 4$ kHz, unless otherwise specified.)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
	VOUT1	1x Mode	1.2		3	V
Output Voltage	VOUT2	2x Mode	5.2	_	6	V
	VOUT3	3x Mode (Note 2)	7.2	_	9.1	V
	IDD11	1x Mode, C _{PIEZO} = No Load	_	105	_	μΑ
Operating Current 1	IDD12	2x Mode, C _{PIEZO} = No Load	_	249	_	μΑ
	IDD13	3x Mode, C _{PIEZO} = No Load	_	354	_	μΑ
	IDD21	1x Mode, Single-ended application	_	0.38	_	mA
Operating Current 2	IDD22	2x Mode, Single-ended application	_	1.33	_	mA
	IDD23	3x Mode, Single-ended application	_	2.8	_	mA
	IDD31	1x Mode, Differential application	_	1.1	_	mA
Operating Current 3	IDD32	2x Mode, Differential application	_	4.46	_	mA
	IDD33	3x Mode, Differential application	_	9.83	_	mA
Shutdown Current	ISD	DIN = 0V	_	8	20	nA
Input Frequency	fIN	Rectangular pulse	_	3	_	kHz
Oscillating Frequency	$f_{ m OSC}$	_	_	200	_	kHz
	toni	1x Mode, From DIN signal High to 90% V _{OUT} steady state	_	95	_	μs
VOUT Start Delay Time	t _{ON2}	2x Mode, From DIN signal High to 90% V _{OUT} steady state	_	310	_	μs
	t _{ON3}	3 x Mode From DIN signal High to 90% V _{OUT} steady state	_	390		μs
Shutdown Delay Time	$t_{ m OFF}$	DIN = H- > L	_	42	_	ms
Output Short-Circuit Current	ISC	_		40	_	mA
Control Terminal Voltage H	VIH	EN1, EN2, DIN pins	0.8*V _{IN}	_	VIN	V
Control Terminal Voltage L	VIL	EN1, EN2,DIN pins	0	_	0.2*V _{IN}	V
Control Terminal Current 1	IIH1	DIN = 3V	_	1.7	_	μΑ
Control Terminal Current 2	IIH2	$V_{EN1} = 3V$, DIN = $3V$	_	1.7	_	μΑ
Control Terminal Current 3	IIH3	$V_{EN1} = 3V$, DIN = $0V$	_		1	μΑ



CHARGE PUMP MODE SETTING

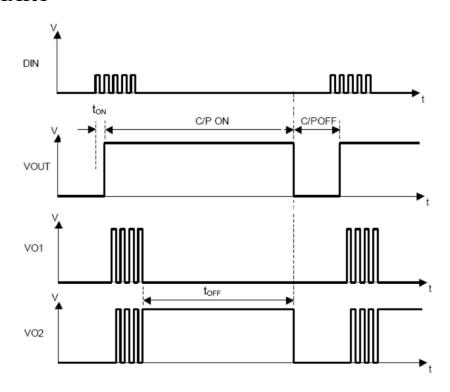
QFN3*3_12/QFN3*3_16 MODE SETTING

DIN	EN1	EN2	MODE
0		-	Shutdown Mode
1	0	0	Shutdown Mode
1	0	1	1x Mode
1	1	0	2x Mode
1	1	1	3x Mode

DFN2*2 MODE SETTING

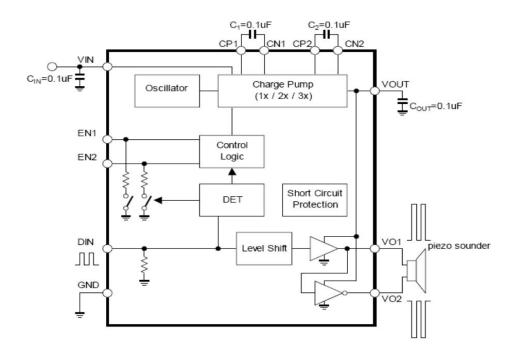
DIN	EN	MODE
0		Shunt down Mode
1	0	2x mode
1	1	3x mode

TIMING CHART

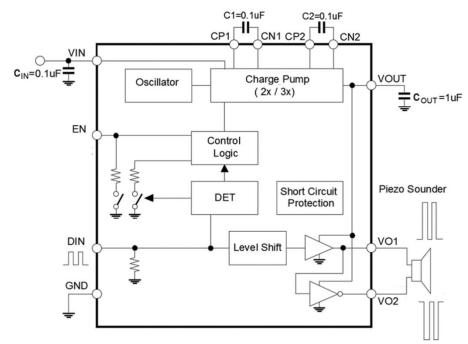




APPLICATION CIRCUIT



QFN3*3_12/QFN3*3_16 Application

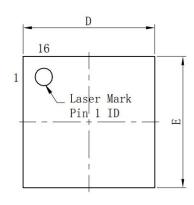


DFN2*2_10 Application

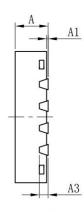


PACKAGE INFORMATION(QFN3*3_16)

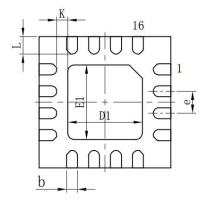
标注	最小	标准	最大	标注	最小	标准	最大
A	0.70	0. 75	0.80	D1	1.60	1. 70	1. 80
A1	0.00	-	0.05	E1	1. 60	1. 70	1. 80
A3		0. 203REF		е		0. 50TYP	
b	0. 20	0. 25	0.30	K	0. 20		1
D	2. 90	3. 00	3. 10	L	0.30	0.40	0. 50
Е	2. 90	3. 00	3. 10				



Top View



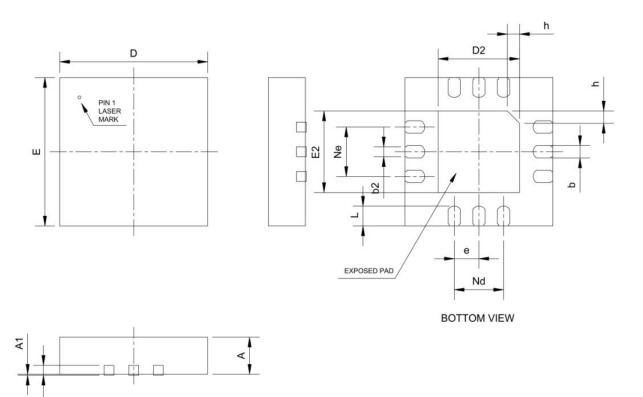
Side View



Bottom View



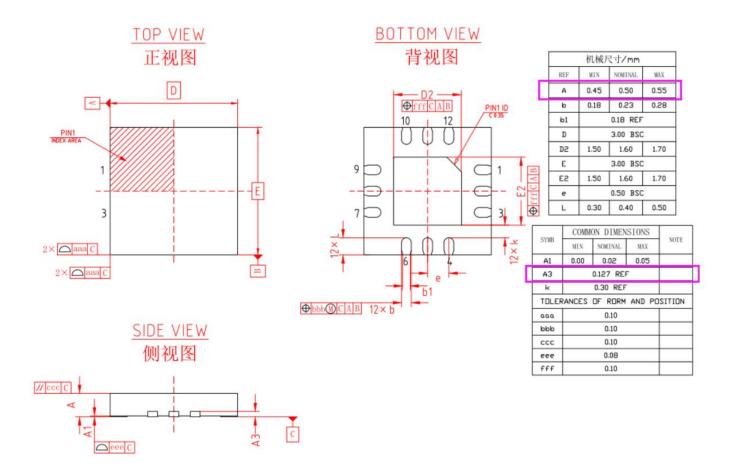
PACKAGE INFORMATION(QFN3*3_12)



Symbol	Min	Nom	Max	Unit
	F	ACKAGE DIMENSION	S	
Α	0.70	0.75	0.80	mm
A1		0.02	0.05	mm
b	0.20	0.25	0.30	mm
b2	0.15	0.20	0.25	mm
С	0.18	0.20	0.25	mm
D	2.90	3.00	3.10	mm
D2 (Exposed.pad)	1.55	1.65	1.75	mm
е		0.50 BSC		mm
Ne		1.00 BSC		mm
Nd		1.00 BSC		mm
E	2.90	3.00	3.10	mm
E2 (Exposed.pad)	1.55	1.65	1.75	mm
L	0.35	0.40	0.45	mm
h	0.20	0.25	0.30	mm

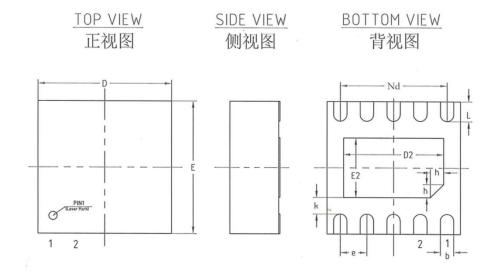


PACKAGE INFORMATION(QFN3*3_12)

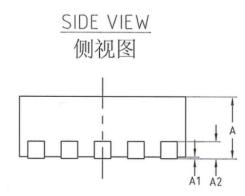




PACKAGE INFORMATION(DFN2*2_10)



	机械万	マサ/mm	
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
Α	0.70	0.75	0.80
A1	-	0.02	0.05
A2	0.203 REF		
b	0.15	0.20	0.25
D	1.90	2.00	2.10
DS	1.45	1.50	1.55
Ε	1.90	2.00	2.10
E2	0.85	0.90	0.95
6	0.40 BSC		
K	0.20	0.25	0.30
L	0.25	0.30	0.35
h	0.15	0.20	0.25
Nd	1.60 BSC		





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REVISION HISTORY

Document revision history

Data	Version	Changes	
26-Aug-2018	Ver1.0	First issue DFN10 Spec	
17-Jan-2025	Ver2.5	Update the package	
17-Mar-2025	Ver2.6	Update the ISD current	
16-Jul-2025	Ver2.7	Add the DFN package information	